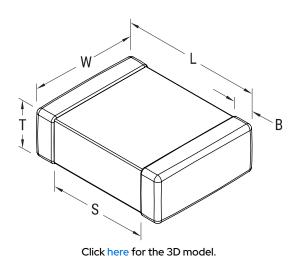


C1206F124K1RACTU

Specifications

Insulation Resistance

Aliases (C1206F124K1RAC7800) SMD Comm X7R FO, Ceramic, 0.12 uF, 10%, 100 VDC, X7R, SMD, MLCC, Open Mode, Temperature Stable, 1206, 1.5 mm



General Information	
Series	SMD Comm X7R FO
Style	SMD Chip
Description	SMD, MLCC, Open Mode, Temperature Stable
Features	Open Mode, Temperature Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	25 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1206
L	3.2mm +/-0.2mm
W	1.6mm +/-0.2mm
Т	0.9mm +/-0.20mm
S	1.5mm MIN
В	0.5mm +/-0.25mm

Capacitance	0.12 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	100 VDC
Dielectric Withstanding Voltage	250 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	2.5% 1 kHz 1.0 Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours

8.3333 GOhms

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	4000

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